

| Processing/Physical Characteristics | dry / cond | Unit | Test Standard |
|--|------------|------|-----------------|
| ISO Data | | | |
| ^[C] Molding shrinkage, parallel | 1.2 / * | % | ISO 294-4, 2577 |
| ^[C] Molding shrinkage, normal | 1.3 / * | % | ISO 294-4, 2577 |

[C]: CAMPUS

| Mechanical properties | dry / cond | Unit | Test Standard |
|--|-------------|-------------------|---------------|
| ISO Data | | | |
| ^[C] Tensile Modulus | 3000 / 1100 | MPa | ISO 527 |
| ^[C] Stress at break | 50 / - | MPa | ISO 527 |
| ^[C] Strain at break | 10 / - | % | ISO 527 |
| Flexural modulus, 23°C | 2800 / 1000 | MPa | ISO 178 |
| Flexural strength | 100 / 40 | MPa | ISO 178 |
| ^[C] Charpy notched impact strength, +23°C | 3.5 / 84 | kJ/m ² | ISO 179/1eA |

[C]: CAMPUS

| Thermal properties | dry / cond | Unit | Test Standard |
|---|------------|-------|-----------------|
| ISO Data | | | |
| ^[C] Melting temperature, 10°C/min | 222 / * | °C | ISO 11357-1/-3 |
| ^[C] Temp. of deflection under load, 1.80 MPa | 60 / * | °C | ISO 75-1/-2 |
| ^[C] Temp. of deflection under load, 0.45 MPa | 165 / * | °C | ISO 75-1/-2 |
| ^[C] Burning Behav. at 1.5 mm nom. thickn. | HB / * | class | IEC 60695-11-10 |
| Yellow Card available | yes / * | - | - |

[C]: CAMPUS

| Electrical properties | dry / cond | Unit | Test Standard |
|------------------------------------|------------|-------|---------------|
| ISO Data | | | |
| ^[C] Volume resistivity | 1E13 / - | Ohm*m | IEC 62631-3-1 |
| ^[C] Surface resistivity | * / 1E12 | Ohm | IEC 62631-3-2 |

[C]: CAMPUS

| Other properties | dry / cond | Unit | Test Standard |
|------------------------|------------|-------------------|---------------|
| ^[C] Density | 1140 / - | kg/m ³ | ISO 1183 |

[C]: CAMPUS

Characteristics

Processing

Injection Molding

Delivery form

Black